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Chicago, Illinois 60601-6780

ASSIGNMENT OF APPLICATION FOR PATENT

WHEREAS, WE,

Nori YOSHIHARA of c/o Toyo Boseki Kabushiki Kaisha, Research Institute,
1-1, Katata 2-chome, Ohtsu-shi, Shiga-ken, Japan

(full name and address, including postal code, of first inventor)

Akira TANIGUCHI of c/o Toyo Boseki Kabushiki Kaisha, Research Institute,
1-1, Katata 2-chome, Ohtsu-shi, Shiga-ken, Japan

(full name and address, including postal code, of second inventor)

(full name and address, including postal code, of third inventor)

(full name and address, including postal code, of fourth inventor)

(full name and address, including postal code, of fifth inventor)

(full name and address, including postal code, of sixth inventor)

respectively, have invented and own a certain new and useful invention entitled:

RESIN COMPOSITION FOR HIGH-FREQUENCY BONDING

for which invention we have executed an application for Letters Patent of the United States, for which application for Letters Patent of the United States has been filed on October 11, 2002, under Serial No. 10/269,677; and

WHEREAS,

Toyo Boseki Kabushiki Kaisha of 2-8, Dojimahama 2-chome, Kita-ku, Osaka-shi,

(full name and address, including postal code, of assignee)

Osaka-fu, Japan

(hereinafter referred to as Assignee) is desirous of acquiring the entire right, title, and interest in and under the invention, the application, and the United States Letters Patent to be obtained therefor.

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that for good and valuable considerations, the receipt and sufficiency whereof are hereby acknowledged, we hereby assign and set over to the Assignee and the Assignee's legal representatives, successors and assigns, the entire right, title, and interest in and to the invention, the application, and the Letters Patent that may or shall issue thereon; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue the Letters Patent to the above-mentioned Assignee agreeably with the terms of this Assignment.

WE HEREBY AUTHORIZE the above-mentioned Assignee to insert in this instrument the filing date and serial number of the application.

WE DO HEREBY COVENANT and agree with the Assignee that we will not execute any writing or do any act whatsoever conflicting with these presents, and that we will at any time upon request, without further or additional consideration, but at the expense of the Assignee, execute such additional assignments and other writings and do such additional acts as the Assignee may deem necessary or desirable to perfect the Assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, divisional, continuation, renewal, reissued, or extended Letters Patent of the United States on the invention, and in enforcing any rights or choses in action accruing as a result of such applications or patents, and by executing preliminary statements and other affidavits, it being understood that the foregoing covenant and agreement shall bind, and inure to the benefit of, the assigns and legal representatives of both parties.

IN WITNESS WHEREOF, we have hereunder set our hands on the dates shown below:

Nori Yoshihara
(Signature of first inventor) Nori YOSHIHARA

November 25, 2002
(Date)

Akito Hamano
Witness Akito HAMANO Date

Nov. 25, 2002

Akira Taniguchi
(Signature of second inventor) Akira TANIGUCHI

November 25, 2002
(Date)

Machiko Tanaka
Witness Machiko TANAKA Date

Nov. 25, 2002

(Signature of third inventor)

(Date)

Witness Date

(Signature of fourth inventor)

(Date)

Witness Date

(Signature of fifth inventor)

(Date)

Witness Date

(Signature of sixth inventor)

(Date)

Witness Date